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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08ka102-i-ss

1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC24F08KA101
- PIC24F16KA101
- PIC24F08KA102
- PIC24F16KA102

The PIC24F16KA102 family introduces a new line of extreme low-power Microchip devices: a 16-bit microcontroller family with a broad peripheral feature set and enhanced computational performance. It also offers a new migration option for those high-performance applications, which may be outgrowing their 8-bit platforms, but do not require the numerical processing power of a digital signal processor.

1.1 Core Features

1.1.1 16-BIT ARCHITECTURE

Central to all PIC24F devices is the 16-bit modified Harvard architecture, first introduced with Microchip's dsPIC® digital signal controllers. The PIC24F CPU core offers a wide range of enhancements, such as:

- 16-bit data and 24-bit address paths with the ability to move information between data and memory spaces
- Linear addressing of up to 12 Mbytes (program space) and 64 Kbytes (data)
- A 16-element working register array with built-in software stack support
- A 17 x 17 hardware multiplier with support for integer math
- Hardware support for 32-bit by 16-bit division
- An instruction set that supports multiple addressing modes and is optimized for high-level languages, such as C
- Operational performance up to 16 MIPS

1.1.2 POWER-SAVING TECHNOLOGY

All of the devices in the PIC24F16KA102 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **On-the-Fly Clock Switching:** The device clock can be changed under software control to the Timer1 source or the internal, low-power RC oscillator during operation, allowing users to incorporate power-saving ideas into their software designs.
- **Doze Mode Operation:** When timing-sensitive applications, such as serial communications, require the uninterrupted operation of peripherals, the CPU clock speed can be selectively reduced, allowing incremental power savings without missing a beat.
- **Instruction-Based Power-Saving Modes:** There are three instruction-based power-saving modes:
  - Idle Mode: The core is shut down while leaving the peripherals active.
  - Sleep Mode: The core and peripherals that require the system clock are shut down, leaving the peripherals that use their own clock, or the clock from other devices, active.
  - Deep Sleep Mode: The core, peripherals (except RTCC and DSWDT), Flash and SRAM are shut down.

1.1.3 OSCILLATOR OPTIONS AND FEATURES

The PIC24F16KA102 family offers five different oscillator options, allowing users a range of choices in developing application hardware. These include:

- Two Crystal modes using crystals or ceramic resonators.
- Two External Clock modes offering the option of a divide-by-2 clock output.
- Two Fast Internal Oscillators (FRCs): One with a nominal 8 MHz output and the other with a nominal 500 kHz output. These outputs can also be divided under software control to provide clock speed as low as 31 kHz or 2 kHz.
- A Phase Locked Loop (PLL) frequency multiplier, available to the External Oscillator modes and the 8 MHz FRC oscillator, which allows clock speeds of up to 32 MHz.
- A separate Internal RC oscillator (LPRC) with a fixed 31 kHz output, which provides a low-power option for timing-insensitive applications.

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

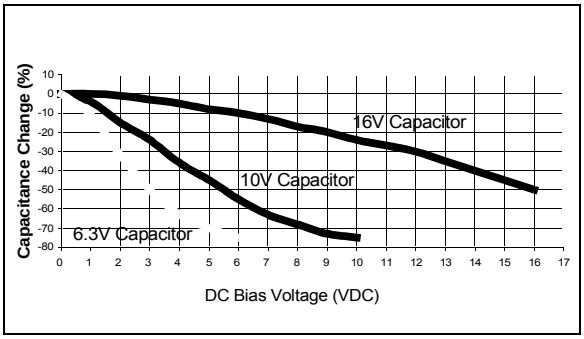
Typical low-cost, 10 μF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R), or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 μF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 3.3V or 2.5V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGC and PGD pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGC and PGD pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., PGCx/PGDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to

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FIGURE 3-1: PIC24F CPU CORE BLOCK DIAGRAM

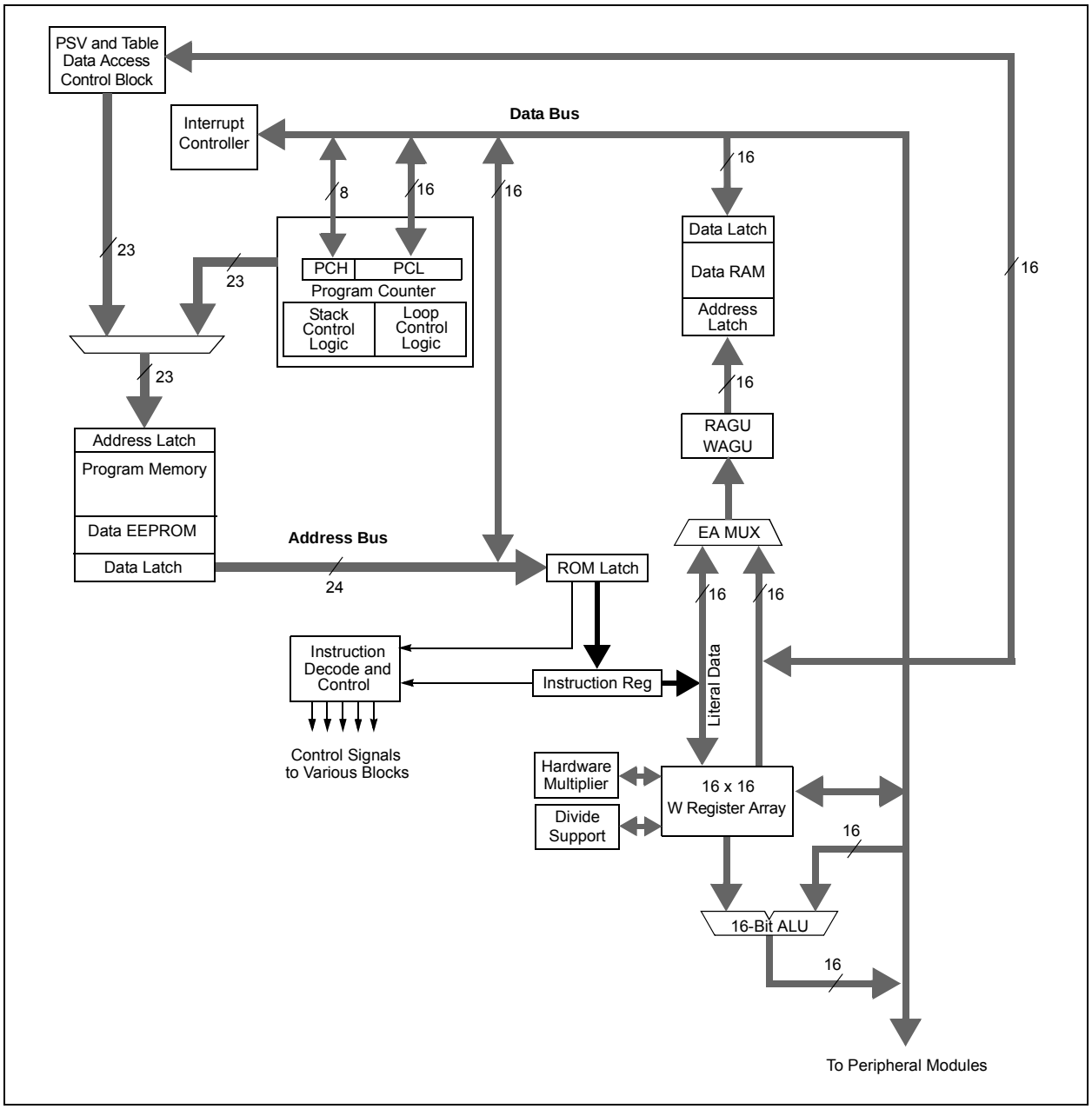

TABLE 3-1: CPU CORE REGISTERS

Register(s) Name	Description
W0 through W15	Working Register Array
PC	23-Bit Program Counter
SR	ALU STATUS Register
SPLIM	Stack Pointer Limit Value Register
TBLPAG	Table Memory Page Address Register
PSVPAG	Program Space Visibility Page Address Register
RCOUNT	Repeat Loop Counter Register
CORCON	CPU Control Register

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7.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) will have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer (OST) has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

7.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it will begin to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device will automatically switch to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine (TSR).

7.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the PIC24F CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset with the exception of four registers. The Reset value for the Reset Control register, RCON, will depend on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, will depend on the type of Reset and the programmed values of the FNOSC bits in the Flash Configuration Word (FOSCSEL); see Table 7-2. The RCFGCAL and NVMCON registers are only affected by a POR.

7.4 Deep Sleep BOR (DSBOR)

Deep Sleep BOR is a very low-power BOR circuitry, used when the device is in Deep Sleep mode. Due to low-current consumption, accuracy may vary.

The DSBOR trip point is around 2.0V. DSBOR is enabled by configuring DSBOREN (FDS<6>) = 1. DSBOREN will re-arm the POR to ensure the device will reset if V_{DD} drops below the POR threshold.

7.5 Brown-out Reset (BOR)

The PIC24F16KA102 family devices implement a BOR circuit, which provides the user several configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> Configuration bits (FPOR<6:5,1:0>). There are a total of four BOR configurations, which are provided in Table 7-3.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below the set threshold point will reset the device. The chip will remain in BOR until V_{DD} rises above threshold.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above the threshold. Then, it will keep the chip in Reset for an additional time delay, T_{PWRT}, if V_{DD} drops below the threshold while the Power-up Timer is running. The chip goes back into a BOR and the Power-up Timer will be initialized. Once V_{DD} rises above the threshold, the Power-up Timer will execute the additional time delay.

BOR and the Power-up Timer are independently configured. Enabling the BOR Reset does not automatically enable the PWRT.

7.5.1 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the control bit, SBOREN (RCON<13>). Setting SBOREN enables the BOR to function as previously described. Clearing the SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise, it is read as '0'.

Placing BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change the BOR configuration. It also allows the user to tailor the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when the BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits; it can not be changed in software.

REGISTER 8-8: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	R/W-0, HS	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	CTMUIF	—	—	—	—	HLVDIF
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0
—	—	—	—	CRCIF	U2ERIF	U1ERIF	—
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **CTMUIF:** CTMU Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **HLVDIF:** High/Low-Voltage Detect Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **CRCIF:** CRC Generator Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **U2ERIF:** UART2 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **U1ERIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **Unimplemented:** Read as '0'

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REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enabled bit
If FSCM is enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **Unimplemented:** Read as '0'

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enable secondary oscillator
0 = Disable secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiate an oscillator switch to clock source specified by NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSC Configuration bits.
2: Also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.

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9.4 Clock Switching Operation

With few limitations, applications are free to switch between any of the four clock sources (POSC, SOSC, FRC and LPRC) under software control and at any time. To limit the possible side effects that could result from this flexibility, PIC24F devices have a safeguard lock built into the switching process.

Note:	The Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMDx Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch between the different primary submodes without reprogramming the device.

9.4.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 26.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and FSCM function are disabled; this is the default setting.

The NOSCx control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSCx bits (OSCCON<14:12>) will reflect the clock source selected by the FNOSCx Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled; it is held at '0' at all times.

9.4.2 OSCILLATOR SWITCHING SEQUENCE

At a minimum, performing a clock switch requires this basic sequence:

1. If desired, read the COSCx bits (OSCCON<14:12>), to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSCx bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSCx bits with the new value of the NOSCx bits. If they are the same, then the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK (OSCCON<5>) and CF (OSCCON<3>) bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware will wait until the OST expires. If the new source is using the PLL, then the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSCx bits value is transferred to the COSCx bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT, FSCM or RTCC with LPRC as clock source are enabled) or SOSC (if SOSCEN remains enabled).

Note 1:	The processor will continue to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.
2:	Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

11.0 I/O PORTS

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the I/O ports, refer to the *"PIC24F Family Reference Manual"*, **Section 12. "I/O Ports with Peripheral Pin Select (PPS)"** (DS39711). Note that the PIC24F16KA102 family devices do not support Peripheral Pin Select features.

All of the device pins (except VDD and VSS) are shared between the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

11.1 Parallel I/O (PIO) Ports

A parallel I/O port that shares a pin with a peripheral is, in general, subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through", in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 displays how ports are shared with other peripherals and the associated I/O pin to which they are connected.

When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin may be read, but the output driver for the parallel port bit will be disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin may be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the Data Latch register (LATx), read the latch. Writes to the latch, write the latch. Reads from the port (PORTx), read the port pins, while writes to the port pins, write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. That means the corresponding LATx and TRISx registers, and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

Note:	The I/O pins retain their state during Deep Sleep. They will retain this state at wake-up until the software restore bit (RELEASE) is cleared.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE

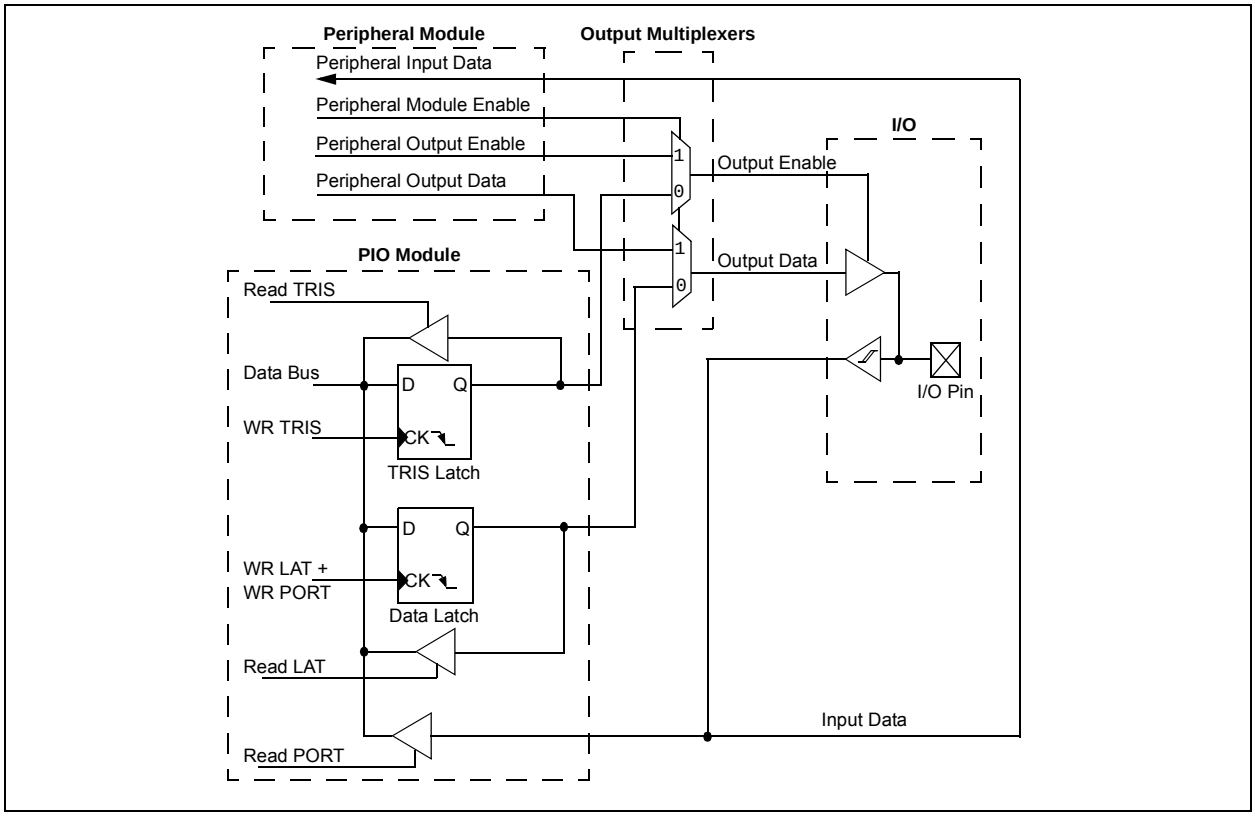


FIGURE 13-2: TIMER2 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM

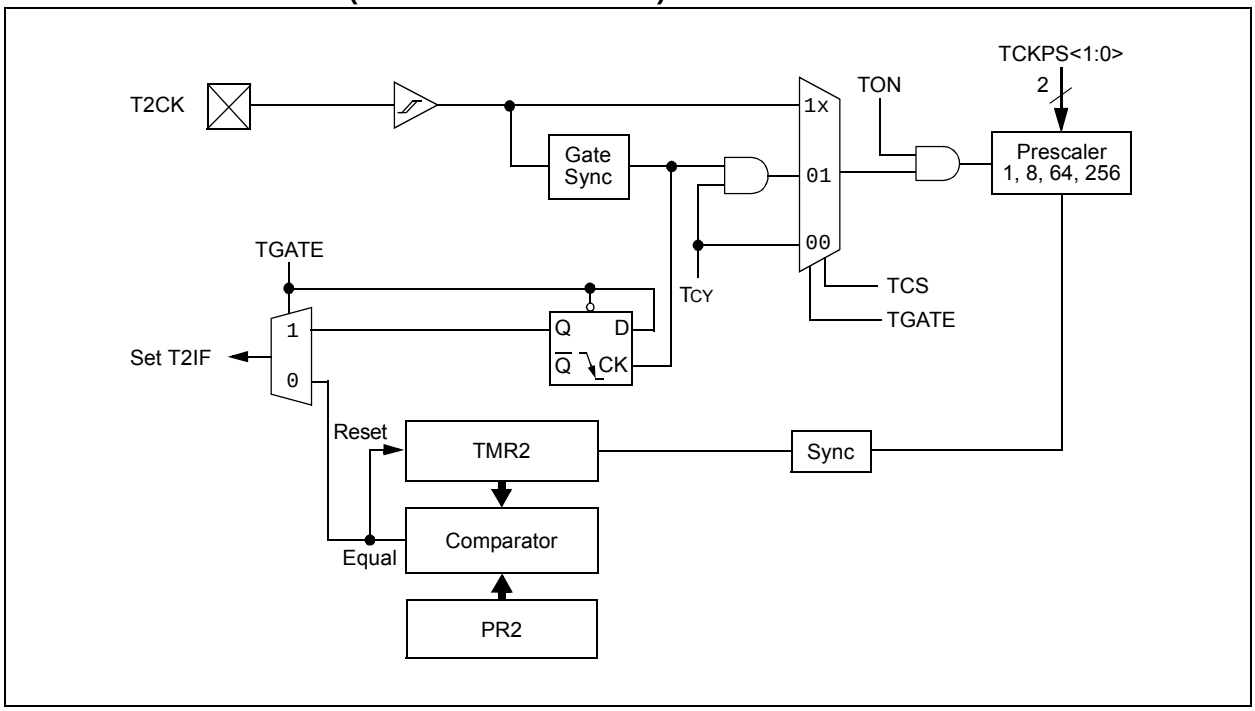
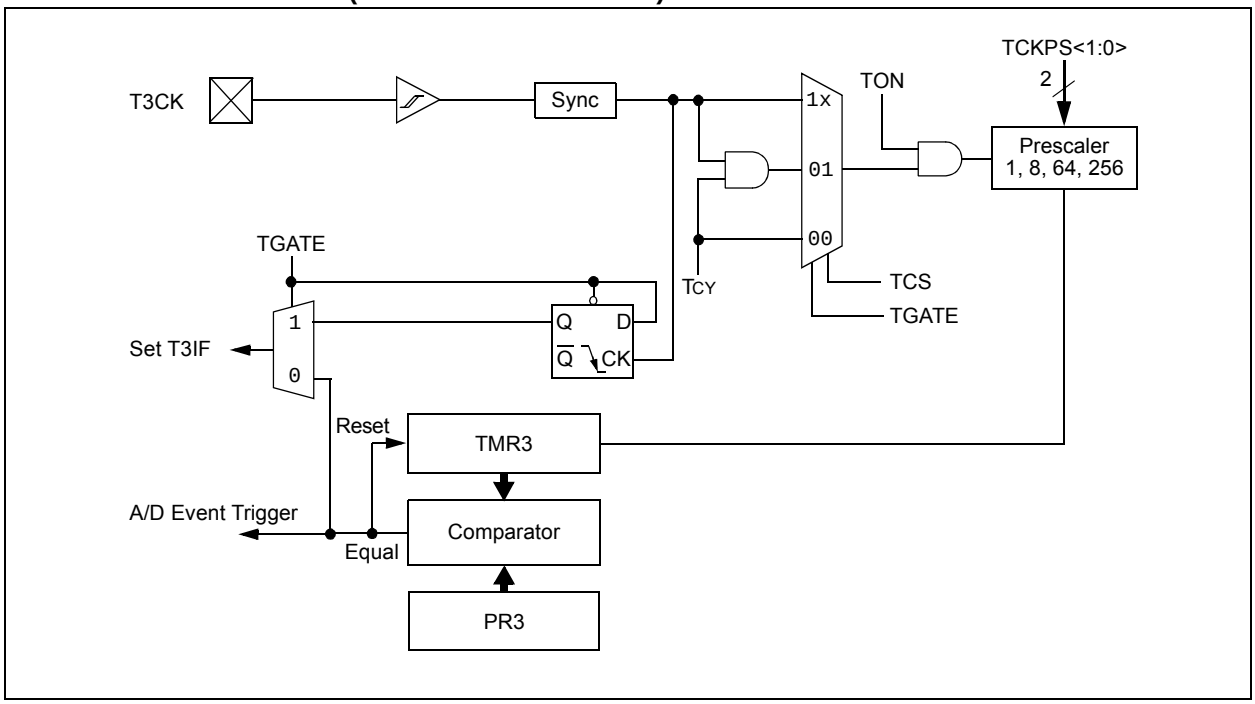


FIGURE 13-3: TIMER3 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM



NOTES:

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16.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Serial Peripheral Interface, refer to the *"PIC24F Family Reference Manual"*, **Section 23. "Serial Peripheral Interface (SPI)"** (DS39699).

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial data EEPROMs, shift registers, display drivers, A/D Converters, etc. The SPI module is compatible with the SPI and SIOP interfaces from Motorola®.

The module supports operation in two buffer modes. In Standard mode, data is shifted through a single serial buffer. In Enhanced Buffer mode, data is shifted through an 8-level FIFO buffer.

Note:	Do not perform read-modify-write operations (such as bit-oriented instructions) on the SPI1BUF register in either Standard or Enhanced Buffer mode.

The module also supports a basic framed SPI protocol while operating in either Master or Slave mode. A total of four framed SPI configurations are supported.

The SPI serial interface consists of four pins:

- SDI1: Serial Data Input
- SDO1: Serial Data Output
- SCK1: Shift Clock Input or Output
- $\overline{SS1}$: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPI module can be configured to operate using 2, 3 or 4 pins. In the 3-pin mode, $\overline{SS1}$ is not used. In the 2-pin mode, both SDO1 and $\overline{SS1}$ are not used.

Block diagrams of the module in Standard and Enhanced Buffer modes are displayed in Figure 16-1 and Figure 16-2.

The devices of the PIC24F16KA102 family offer one SPI module on a device.

Note:	In this section, the SPI module is referred to as SPI1, or separately as SPI1. Special Function Registers (SFRs) will follow a similar notation. For example, SPI1CON1 or SPI1CON2 refers to the control register for the SPI1 module.

To set up the SPI module for the Standard Master mode of operation:

1. If using interrupts:
   a) Clear the respective SPI1IF bit in the IFS0 register.
   b) Set the respective SPI1IE bit in the IEC0 register.
   c) Write the respective SPI1IPx bits in the IPC2 register to set the interrupt priority.
2. Write the desired settings to the SPI1CON1 and SPI1CON2 registers with the MSTEN bit (SPI1CON1<5>) = 1.
3. Clear the SPIROV bit (SPI1STAT<6>).
4. Enable SPI operation by setting the SPIEN bit (SPI1STAT<15>).
5. Write the data to be transmitted to the SPI1BUF register. Transmission (and reception) will start as soon as data is written to the SPI1BUF register.

To set up the SPI module for the Standard Slave mode of operation:

1. Clear the SPI1BUF register.
2. If using interrupts:
   a) Clear the respective SPI1IF bit in the IFS0 register.
   b) Set the respective SPI1IE bit in the IEC0 register.
   c) Write the respective SPI1IP bits in the IPC2 register to set the interrupt priority.
3. Write the desired settings to the SPI1CON1 and SPI1CON2 registers with the MSTEN bit (SPI1CON1<5>) = 0.
4. Clear the SMP bit.
5. If the CKE bit is set, then the SSEN bit (SPI1CON1<7>) must be set to enable the $\overline{SS1}$ pin.
6. Clear the SPIROV bit (SPI1STAT<6>).
7. Enable SPI operation by setting the SPIEN bit (SPI1STAT<15>).

REGISTER 16-2: SPI1CON1: SPI1 CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **DISSCK:** Disable SCK1 pin bit (SPI Master modes only)
1 = Internal SPI clock is disabled, pin functions as I/O
0 = Internal SPI clock is enabled

bit 11 **DISSDO:** Disables SDO1 pin bit
1 = SDO1 pin is not used by module; pin functions as I/O
0 = SDO1 pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPI1 Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
Slave mode:
SMP must be cleared when SPI1 is used in Slave mode.

bit 8 **CKE:** SPI1 Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (see bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (see bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)
1 = $\overline{SS1}$ pin is used for Slave mode
0 = $\overline{SS1}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
.
.
.
000 = Secondary prescale 8:1

Note 1: The CKE bit is not used in the Framed SPI modes. The user should program this bit to '0' for the Framed SPI modes (FRMEN = 1).

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EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPI CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCK FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

2: SCK1 frequencies are indicated in kHz.

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REGISTER 17-2: I2C1STAT: I2C1 STATUS REGISTER (CONTINUED)

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware is set or clear when Start, Repeated Start or Stop is detected.

bit 2 **R/$\overline{W}$:** Read/$\overline{Write}$ Information bit (when operating as I^2C slave)
1 = Read – indicates the data transfer is output from slave
0 = Write – indicates the data transfer is input to slave
Hardware is set or clear after reception of I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive complete, I2C1RCV is full
0 = Receive not complete, I2C1RCV is empty
Hardware is set when I2C1RCV is written with received byte; hardware is clear when software reads I2C1RCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2C1TRN is full
0 = Transmit complete, I2C1TRN is empty
Hardware is set when software writes to I2C1TRN; hardware is clear at completion of data transmission.

REGISTER 18-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0(2)	R/W-0(2)
UARTEN	—	USIDL	IREN(1)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/C-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	C = Clearable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
- 0 = UARTx is disabled; all UARTx pins are controlled by port latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when device enters Idle mode
- 0 = Continue module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(1)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Enable bits(2)
- 11 = UxTX, UxRX and UxBCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/UxBCLK pins are controlled by port latches

bit 7 **WAKE:** Wake-up on Start Bit Detect During Sleep Mode Enable bit
- 1 = UARTx will continue to sample the UxRX pin; interrupt generated on falling edge, bit is cleared in hardware on the following rising edge
- 0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Enable Loopback mode
- 0 = Loopback mode is disabled

bit 5 **ABAUD:** Auto-Baud Enable bit
- 1 = Enable baud rate measurement on the next character – requires reception of a Sync field (55h); cleared in hardware upon completion
- 0 = Baud rate measurement is disabled or completed

bit 4 **RXINV:** Receive Polarity Inversion bit
- 1 = UxRX Idle state is '0'
- 0 = UxRX Idle state is '1'

Note 1: This feature is only available for the 16x BRG mode (BRGH = 0).

2: Bit availability depends on pin availability.

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REGISTER 23-1: CMxCON: COMPARATOR x CONTROL REGISTERS

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R-0
CON	COE	CPOL	CLPWR	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12 **CLPWR:** Comparator Low-Power Mode Select bit
1 = Comparator operates in Low-Power mode
0 = Comparator does not operate in Low-Power mode

bit 11-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event defined by EVPOL<1:0> has occurred; subsequent triggers and interrupts are disabled until the bit is cleared
0 = Comparator event has not occurred

bit 8 **COUT:** Comparator Output bit
When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt is generated on transition of the comparator output:
If CPOL = 0 (non-inverted polarity):
High-to-low transition only.
If CPOL = 1 (inverted polarity):
Low-to-high transition only.
01 = Trigger/event/interrupt is generated on transition of the comparator output:
If CPOL = 0 (non-inverted polarity):
Low-to-high transition only.
If CPOL = 1 (inverted polarity):
High-to-low transition only.
00 = Trigger/event/interrupt generation is disabled

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 3-2 **EDG1SEL<1:0>:** Edge 1 Source Select bits
11 = CTED1 pin
10 = CTED2 pin
01 = OC1 module
00 = Timer1 module

bit 1 **EDG2STAT:** Edge 2 Status bit
1 = Edge 2 event has occurred
0 = Edge 2 event has not occurred

bit 0 **EDG1STAT:** Edge 1 Status bit
1 = Edge 1 event has occurred
0 = Edge 1 event has not occurred

REGISTER 25-2: CTMUICON: CTMU CURRENT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **ITRIM<5:0>:** Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
.
.
.
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
.
.
.
100010
100000 = Maximum negative change from nominal current

bit 9-8 **IRNG<1:0>:** Current Source Range Select bits
11 = 100 × Base current
10 = 10 × Base current
01 = Base current level (0.55 μA nominal)
00 = Current source is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

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TABLE 29-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(4)**	—	—	—	—	
DI10		I/O Pins	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		OSCI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSCI (HS mode)	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I2C™ Buffer	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SMBus Buffer	VSS	—	0.8	V	SMBus enabled
	VIH(5)	**Input High Voltage(4)**	—	—	—	—	
DI20		I/O Pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	
		Digital Only	0.8 VDD	—	VDD	V	
DI25		$\overline{\text{MCLR}}$	0.8 VDD	—	VDD	V	
DI26		OSCI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSCI (HS mode)	0.7 VDD	—	VDD	V	
DI28		I/O Pins with I2C Buffer:					
		with Analog Functions	0.7 VDD	—	VDD	V	
		Digital Only	0.7 VDD	—	VDD	V	
DI29		I/O Pins with SMBus	2.1	—	VDD	V	2.5V ≤ VPIN ≤ VDD
DI30	ICNPU	**CNx Pull-up Current**	50	250	500	μA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Ports	—	0.050	±0.100	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		VREF+, VREF-, AN0, AN1	—	0.300	±0.500	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$	—	—	±5.0	μA	VSS ≤ VPIN ≤ VDD
DI56		OSCI	—	—	±5.0	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-2 for I/O pin buffer types.

5: VIH requirements are met when internal pull-ups are enabled.

FIGURE 29-16: PWM MODULE TIMING REQUIREMENTS

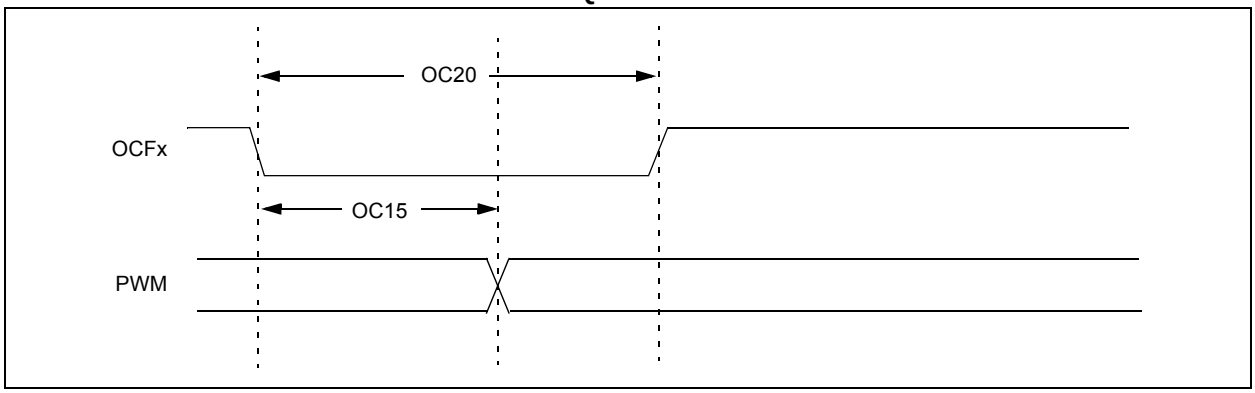


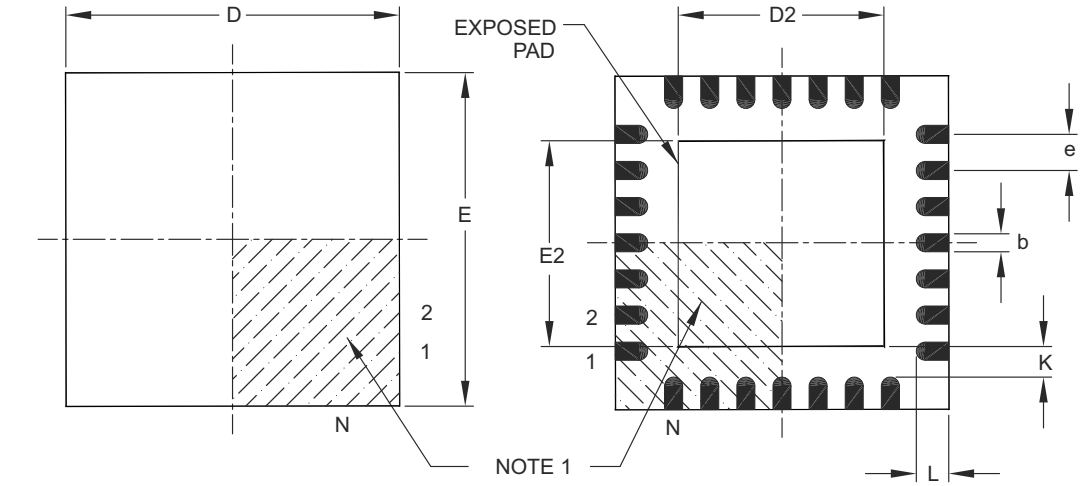
TABLE 29-35: PWM TIMING REQUIREMENTS

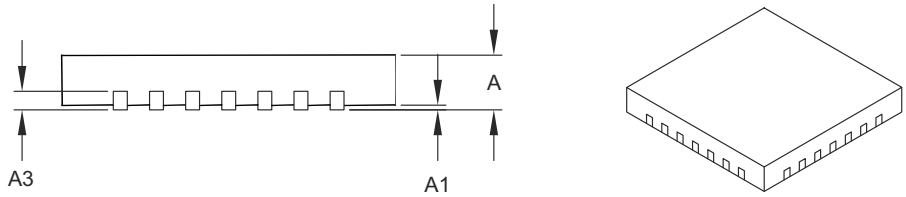
Param. No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
OC15	TFD	Fault Input to PWM I/O Change	—	—	25	ns	VDD = 3.0V, -40°C to +125°C
OC20	TFH	Fault Input Pulse Width	50	—	—	ns	VDD = 3.0V, -40°C to +125°C

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B